Notice of References Cited Application/Control No. 10/549,267 Examiner JOHN M. CORBETT Applicant(s)/Patent Under Reexamination RASCHE ET AL. Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	Α	US-			
	В	US-			
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)			
	U	Bookstein, Principal Warps: Thin-Plate Splines and the Decomposition of Deformations, 6 June 1989, IEEE Transactions on Pattern Analysis and Machine Intelligence, Volume 11, Number 6, Pages 567-585			
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	х				

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).) Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.